

# 4A, 50V - 1000V Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High current capability
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- · General purpose

#### **MECHANICAL DATA**

• Case: DO-214AB (SMC)

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Meet JESD 201 class 2 whisker test

• Polarity: Indicated by cathode band

• Weight: 0.210g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	4	Α		
$V_{RRM}$	50 - 1000	٧		
I <sub>FSM</sub>	100	Α		
T <sub>J MAX</sub>	150	°C		
Package	DO-214AB (SMC)			
Configuration	Single die			









DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)									
PARAMETER	SYMBOL	S4 AH	S4 BH	S4 DH	S4 GH	S4 JH	S4 KH	S4 MH	UNIT
Marking code on the device		S4A	S4B	S4D	S4G	S4J	S4K	S4M	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Forward current	I <sub>F</sub>	4		Α					
Peak forward surge current, 8.3ms single half sine wave superimposed on rated load	I <sub>FSM</sub>	100			А				
Junction temperature	TJ	T <sub>J</sub> - 55 to +150			°C				
Storage temperature	T <sub>STG</sub> - 55 to +150			°C					

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	13	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	47	°C/W	

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 4A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.15	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	· I <sub>R</sub>	-	10	μΑ
	T <sub>J</sub> = 125°C		-	250	μΑ
Junction capacitance	$1MHz, V_R = 4.0V$	CJ	60	-	pF
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	1500	-	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
S4xH	DO-214AB (SMC)	3,000 / Tape & Reel		

#### Notes:

1. "x" defines voltage from 50V(S4AH) to 1000V(S4MH)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

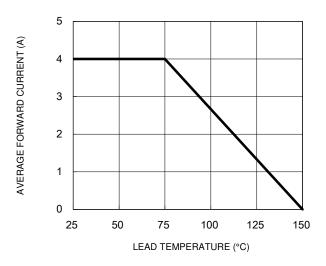


Fig.3 Typical Reverse Characteristics

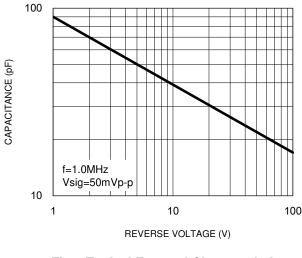
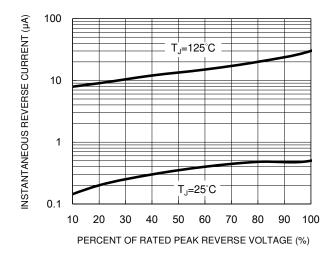


Fig.2 Typical Junction Capacitance

**Fig.4 Typical Forward Characteristics** 



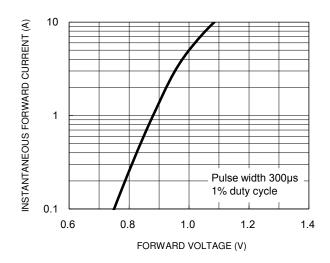
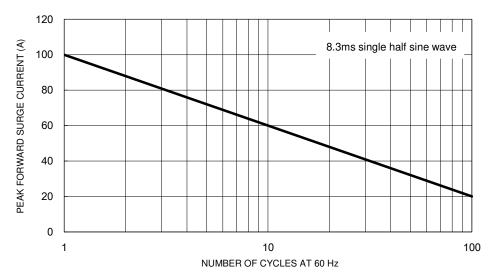


Fig.5 Maximum Non-Repetitive Forward Surge Current



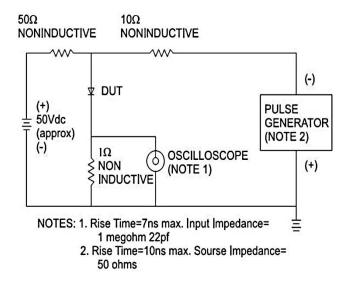


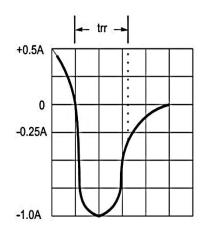
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### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram



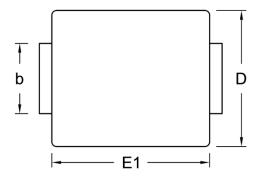


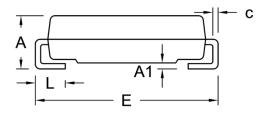




## **PACKAGE OUTLINE DIMENSIONS**

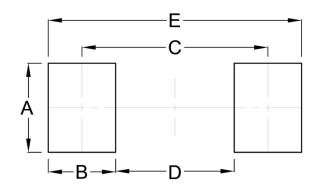
## DO-214AB (SMC)





DIM. Unit (mm)		(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	2.00	2.62	0.079	0.103	
A1	0.10	0.20	0.004	0.008	
b	2.90	3.20	0.114	0.126	
С	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

## **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



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